

STACKABLE LEAD FRAME PACKAGE USING EXPOSED INTERNAL
LEAD TRACES

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ABSTRACT

A die package is formed, which allows additional electrical connections to the die by using internal leads or traces from a lead frame. The internal leads are exposed through an upper or lower surface of the package, thereby allowing an additional die package to be stacked and electrically connected to the underlying die or additional inputs/outputs to underlying external circuitry, such as a printed circuit board.

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